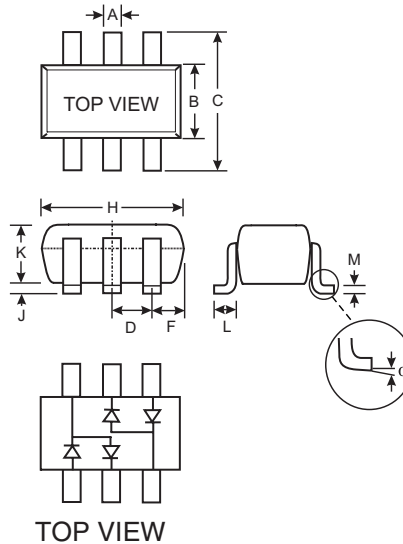


**Features**

- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- Fast Switching
- Low Reverse Capacitance
- **Lead Free/RoHS Compliant (Note 3)**
- "Green" Device, Note 4 and 5

**Mechanical Data**

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Polarity: See Diagram
- Leads: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Copper leadframe).
- Marking: KSU (See Page 3)
- Weight: 0.016 grams (approximate)



SOT-26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
F	—	—	0.55
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
<b>All Dimensions in mm</b>			

**Maximum Ratings** @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Forward Continuous Current (Note 1)	I <sub>FM</sub>	350	mA
Non-Repetitive Peak Forward Surge Current @ t ≤ 1.0s	I <sub>FSM</sub>	1.5	A
Power Dissipation (Note 1)	P <sub>d</sub>	225	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	R <sub>θJA</sub>	444	°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +125	°C

**Electrical Characteristics** @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V <sub>(BR)R</sub>	40	—	—	V	I <sub>R</sub> = 100μA
Forward Voltage Drop	V <sub>F</sub>	—	—	0.37 0.50 0.60	V	I <sub>F</sub> = 20mA I <sub>F</sub> = 100mA I <sub>F</sub> = 200mA
Reverse Current (Note 2)	I <sub>R</sub>	—	—	5.0	μA	V <sub>R</sub> = 30V
Total Capacitance	C <sub>T</sub>	—	50	—	pF	V <sub>R</sub> = 0V, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	10	—	ns	I <sub>F</sub> = I <sub>R</sub> = 200mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

- Notes:
1. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. Short duration test pulse used to minimize self-heating effect.
  3. No purposefully added lead.
  4. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants

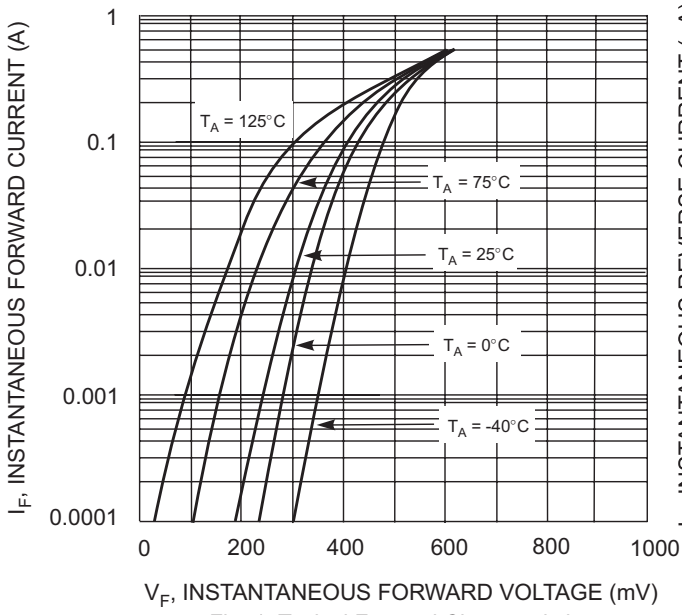


Fig. 1 Typical Forward Characteristics

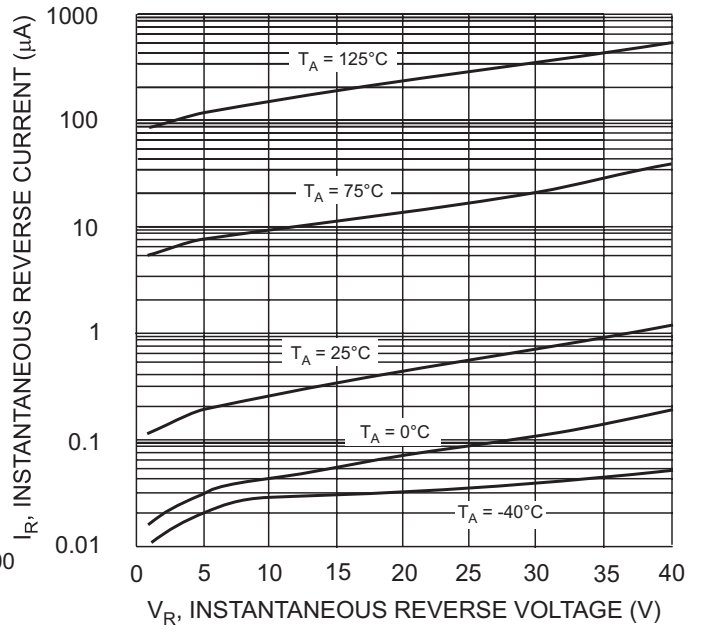


Fig. 2 Typical Reverse Characteristics

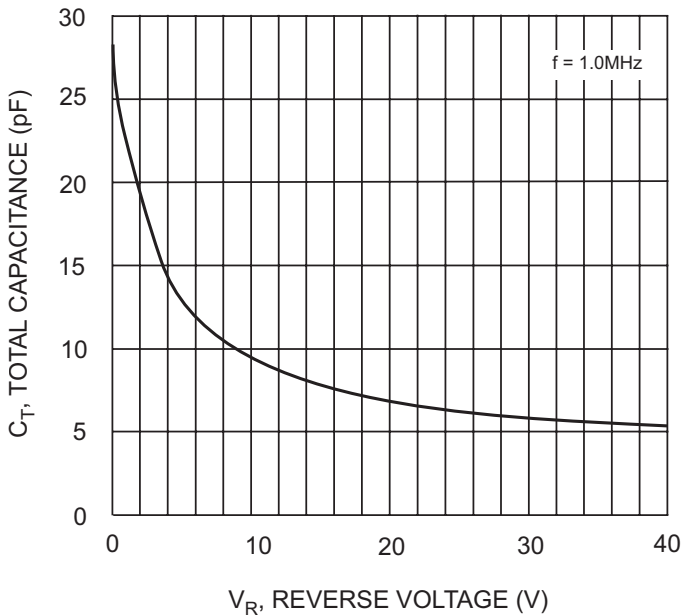


Fig. 3 Typ. Total Capacitance vs. Reverse Voltage

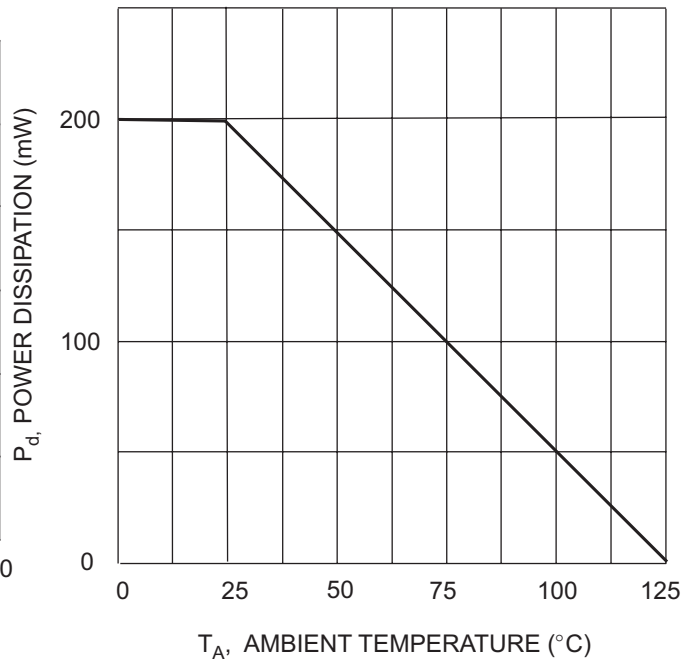


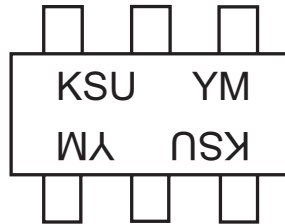
Fig. 4 Power Derating Curve

## Ordering Information (Note 5 & 6)

Device	Packaging	Shipping
SD103ASDM-7-F	SOT-26	3000/Tape & Reel

- Notes:
- Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants
  - For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



KSU = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year ex: T = 2006  
 M = Month ex: 9 = September

### Date Code Key

Year	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	N	P	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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